Materials Declaration Form

IPC	1752	Version	2
Form Type *	Distribute		
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D * : Required Field

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2016-04-08
Contact Name *	Refer to " Supplier Comment" section	Contact Title	Refer to " Supplier Comment" section
Contact Phone *	Refer to " Supplier Comment" section	Contact Email *	Refer to " Supplier Comment" section
Authorized Representative *	Emilio Castelli	Representative Title	APG MD CHAMPION
Representative Phone *	Refer to " Supplier Comment" section	Representative Email *	Refer to " Supplier Comment" section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/online_tech_support.html		

Uncertainty Statement

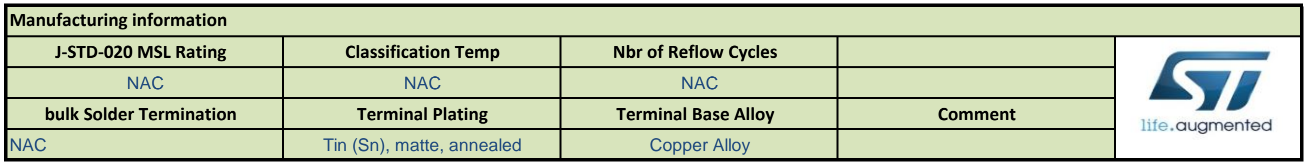
While STMicroelectronics has endeavored to provide information which is accurate and up to date, this document and its contents are provided on a strict 'as is' and 'as available' basis. STMicroelectronics disclaims all warranties, express or implied related to this document and its contents, including but not limited to implied warranties of completeness, truth, accuracy, merchantability, fitness for a particular purpose and non-infringement. ST shall have no responsibility and assumes no liability for any cost, loss or damage of any kind which could arise, directly or indirectly, from the use or inability to use this document and/or its contents.

Legal Statement

Supplier Acceptance *	true	Legal Declaration *	Standard

Legal Statement	Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as omprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	**Mfr Item Name**	**Version**	**Mfr Site**	**Date**
E-TDA7386	H94W*L390BB6	A	SH1A	2016-04-08
	Amount	**UoM**	**Unit type**	**ST ECOPACK Grade**
	7099.40	mg	Each	ECOPACK® 2



Manufacturing information				
J-STD-020 MSL Rating	**Classification Temp**	**Nbr of Reflow Cycles**		life.augmented
NAC	NAC	NAC		
bulk Solder Termination	**Terminal Plating**	**Terminal Base Alloy**	**Comment**	
NAC	Tin (Sn), matte, annealed	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
SMO	29.23x15.7x4.5	25	flat	
Comment				

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	**Response**
Product(s) meets EU RoHS requirement without any exemptions	false
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7a' exemption (other selected exemptions may apply)	**true**
Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Product(s) is obsolete, no information is available	false
Product(s) is unknown, no information is available	false

Exemption Id.	**Description**

QueryList : REACH-17th Dec 2015				
Query				**Response**
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				**true**
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						**Mfr Item Name**	**H94W*L390BB6**					
Homogeneous Material	**Material Group**	**Mass**	**UoM**	**Level**	**Substance Category**	**Substance**	**CAS**	**Exempt**	**Mass**	**UoM**	**Concentration in homogeneous material (ppm)**	**Concentration in product (ppm)**
Die	Other inorganic materials	24.957	mg	supplier	die	Silicon (Si)	7440-21-3		24.042	mg	963337	3386
Die				supplier	metallization	Aluminium (Al)	7429-90-5		0.375	mg	15026	53
Die				supplier	passivation	Silicon Nitride (SiN)	68034-42-4		0.105	mg	4207	15
Die				supplier	passivation	Silicon Oxide(SiO2)	7631-86-9		0.199	mg	7974	28
Die				supplier	back side metallization	Chromium (Cr)	7440-47-3		0.019	mg	761	3
Die				supplier	back side metallization	Gold (Au)	7440-57-5		0.050	mg	2003	7
Die				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.167	mg	6692	24
Leadframe	Copper & its alloys	5239.637	mg	supplier	alloy	Copper (Cu)	7440-50-8		5214.618	mg	995225	734515
Leadframe				supplier	alloy	Iron (Fe)	7439-89-6		2.402	mg	458	338
Leadframe				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		4.386	mg	837	618
Leadframe				supplier	metallization	Nickel (Ni)	7440-02-0		16.900	mg	3225	2380
Leadframe				supplier	metallization	Silver (Ag)	7440-22-4		1.331	mg	254	187
Die attach		15.929	mg	JIG - R	Soft Solder	Lead (Pb)	7439-92-1	7a-Lead in high me	15.531	mg	975014	2188
Die attach				supplier	Soft Solder	Silver (Ag)	7440-22-4		0.239	mg	15004	34
Die attach				supplier	Soft Solder	Tin (Sn)	7440-31-5		0.159	mg	9982	22
Bonding wire				supplier	wire	Copper (Cu)	7440-50-8		4.493	mg	1000000	633
encapsulation		1773.891	mg	supplier	mold compound	Amorphous Silica	7631-86-9		1507.807	mg	850000	212385
encapsulation				supplier	mold compound	Epoxy Cresol Novolak	29690-82-2		106.433	mg	60000	14992
encapsulation				supplier	mold compound	epoxy resin	na		70.956	mg	40000	9995
encapsulation				supplier	mold compound	Phenol resin	na		70.956	mg	40000	9995
encapsulation				supplier	mold compound	Carbon black	1333-86-4		12.417	mg	7000	1749
encapsulation				supplier	mold compound	Bismuth (Bi)	7440-69-9		5.322	mg	3000	750
connections coating	Solder	40.493	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		40.493	mg	1000000	5704